Wire-wound Metal Power Inductors MCOIL<sup>™</sup> LSEN series for General Electronic Equipment for Consumer Wire-wound Metal Power Inductors MCOIL<sup>™</sup> LSEP series for General Electronic Equipment for Consumer Wire-wound Metal Power Inductors MCOIL<sup>™</sup> LLEN series

for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)

Wire-wound Metal Power Inductors MCOIL<sup>™</sup> LLEP series

for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)

## RELIABILITY DATA

1. Operating Temp	erature Range				
Specified Value	-40~+125°C				
Test Methods and Remarks	Including self-generated heat				
2. Storage Temper	ature Range				
Specified Value	-40~+85°C				
Test Methods and Remarks	0 to 40°C for the product with taping.				
3. Rated current					
Specified Value	Within the specified tolerance				
4. Inductance					
Specified Value	Within the specified tolerance				
Test Methods and Remarks	Measuring equipment : LCR Meter (HP 4294A or equivalent) Measuring frequency : 1MHz、0.5V				
5. DC Resistance					
Specified Value	Within the specified tolerance				
Test Methods and Remarks	Measuring equipment : DC ohmmeter (HIOKI 3227 or equivalent)				
6. Self resonance t	requency				
Specified Value	_				
7. Temperature ch					
Specified Value	Inductance change: Within ±15%				
Test Methods and Remarks	Measurement of inductance shall be taken at temperature range within $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ . With reference to inductance value at $+20^{\circ}\text{C}$ , change rate shall be calculated.				
8. Resistance to flo					
Specified Value	No damage				
<b>-</b>	The test samples shall be soldered to the test board by the reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2 mm.  Test board size : 100 × 40 × 1.0 mm  Test board material : Glass epoxy-resin  Solder cream thickness : 0.10 mm  Rod				
Test Methods and Remarks	Solder cream thickness : 0.10 mm  Rod  Board  Test sample  45 ± 2  45 ± 2  Unit[mm]				
9. Insulation resist	ance : between wires				
Specified Value	_				

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10. Insulation resist	ance : betw	ween wire and over	r-coating				
Specified Value	-						
	I						
11. Withstanding vo	ltage : betv	veen wire and over	r-coating				
Specified Value	l –						
12. Adhesion of terr	minal electi	rode					
Specified Value	No abnor	mality.					
			soldered to 1	the test	board by the reflow.		
Test Methods and	Applied force : 10N to X and Y directions.						
Remarks	Duration		: 5s.				
	Solder	cream thickness	: 0.10mm				
13. Resistance to v	ibration						
Specified Value		ce change : Within					
		icant abnormality i					
		samples shall be s hall be submitted			board by the reflow.		
		25 532552					
	Frequ	iency Range	10∼55Hz				
Test Methods		Amplitude			xceed acceleration 1	96m/s²)	
and Remarks	Swee	ping Method	10Hz to 5	5Hz to 1	0Hz for 1min.		-
		Time	Y		For 2 hours on ach	X. Y. and Z axis.	
			Z				
	Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.						
14. Solderability							
Specified Value	At least 90% of surface of terminal electrode is covered by new solder.						
	The test	samples shall be o	dipped in flu	x, and th	en immersed in molte	en solder as shown in below	v table.
Test Methods and	_	nanol solution cont		_			
Remarks		Temperature	245±5 5±0.5				
	Time XImmer	sion denth · All sid			inal shall be immerse	ed.	
	7.(2.1111101)	olon dopen : 7 iii old	oo or mount		mar onan be mimeree	· u.	
15. Resistance to s	oldering he	at					
To. Nesistance to s		ce change : Within	± 10%				
Specified Value		icant abnormality i		e.			
	The test	sample shall be e	exposed to	reflow ov	ven at 230°C for 40	seconds, with peak tempe	rature at $260+0/-5^{\circ}$ C for 5 seconds, 2
Test Methods	times.						
and Remarks	Test board material : Glass epoxy-resin						
	Test board thickness : 1.6mm  Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.						
	recovery	Y . At least Zill's Of	recovery u	iluer tile	Standard Condition a	inter the test, followed by the	ie measurement within 40ms.
16. Thermal shock							
To. Thermal shock	I	I MACIL!	1.100/				
Specified Value		ce change : Within icant abnormality i		e.			
					ooard by the reflow T	The test samples shall be bla	aced at specified temperature for specified
	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles.						
			nditions of 1	cycle		]	
Test Methods	Step	Temperature			Ouration (min)		
and Remarks	1	-40±3			30±3	4	
	3	Room temper			Within 3 30±3	-	
	1 4	T0J T	-		30±3 W:+l-: 0	-	

Room temperature

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Within 3

Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

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17. Damp heat					
Specified Value	Inductance change : Within ±10%  No significant abnormality in appearance.				
Test Methods	The test samples shall be soldered to the test board by the reflow.  The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table.				
and Remarks	Temperature	60±2°C			
	Humidity	90~95%RH			
	Time	500+24/-0 hour			
	Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.				

Specified Value	Inductance change : Within ±10%  No significant abnormality in appearance.				
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow.  The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table.				
	Temperature	60±2°C			
	Humidity	90∼95%RH			
	Applied current	Rated current			
	Time	500+24/-0 hour			

19. Low temperatur	re life test				
Specified Value	Inductance change : Within ±10%  No significant abnormality in appearance.				
Test Methods	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table.				
and Remarks	Temperature	-40±2°C			
	Time	500+24/-0 hour			
	Recovery : At least	2hrs of recovery under the	standard condition after the test, followed by the measurement within 48hrs.		

20. High temperate							
Specified Value	Inductance change	Inductance change: Within ±10%					
	No significant abnormality in appearance.						
Test Methods	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table.						
and Remarks	Temperature	125±2°C					
	Time	500+24/-0 hour					
	Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.						

Specified Value	-
22. Standard condi	tion
	Standard test condition:
	Unless otherwise specified, temperature is 20±15°C and 65±20% of relative humidity.
Specified Value	When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of 20±2°C of
	temperature, 65±5% relative humidity.
	Inductance is in accordance with our measured value.

21. Loading at high temperature life test

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